



#### P-CHANNEL ENHANCEMENT MODE MOSFET

### **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub>	I <sub>D</sub> T <sub>A</sub> = +25°C
-20V	5Ω @ V <sub>GS</sub> = -4.5V	-200mA
	7Ω @ V <sub>GS</sub> = -2.5V	-170mA
	10Ω @ V <sub>GS</sub> = -1.8V	-140mA
	15Ω @ V <sub>GS</sub> = -1.5V	-50mA

#### **Description**

This new generation MOSFET is designed to minimize the on-state resistance ( $R_{DS(ON)}$ ), yet maintain superior switching performance, making it ideal for high efficiency power management applications.

### **Applications**

- DC-DC Converters
- Power Management Functions

### **Features and Benefits**

- P-Channel MOSFET
- Low On-Resistance
- Very Low Gate Threshold Voltage V<sub>GS(TH)</sub>
- Low Input Capacitance
- Fast Switching Speed
- Ultra-Small Surfaced Mount Package
- Ultra-Low Package Profile, 0.4mm Maximum Package Height
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

#### **Mechanical Data**

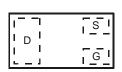
- Case: X2-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound;
  UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @4
- Weight: 0.001 grams (Approximate)



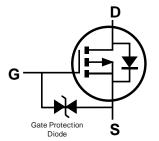




**Bottom View** 



Top View Internal Schematic



Equivalent Circuit

#### **Ordering Information** (Note 4)

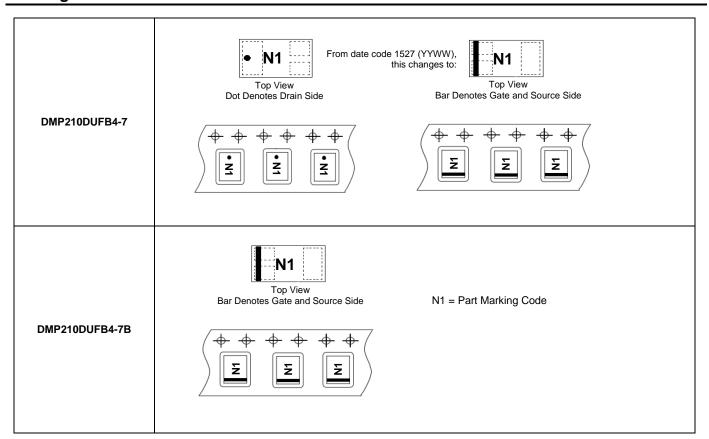
Part Number	Case	Packaging
DMP210DUFB4-7	X2-DFN1006-3	3,000/Tape & Reel
DMP210DUFB4-7B	X2-DFN1006-3	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.



# **Marking Information**





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Characteristic	Symbol	Value	Units		
Drain-Source Voltage	$V_{DSS}$	-20	V		
Gate-Source Voltage	$V_{GSS}$	±10	V		
Continuous Drain Current (Note 5) V <sub>GS</sub> = -4.5V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I <sub>D</sub>	-200 -160	mA
Continuous Drain Current (Note 5) V <sub>GS</sub> = -1.8V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	ID	-140 -110	mA
Pulsed Drain Current	$T_P = 10$	μs	I <sub>DM</sub>	-600	mA

### **Thermal Characteristics**

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 5)	$P_{D}$	350	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	357	°C/W
Operating and Storage Temperature Range	$T_{J_i} T_{STG}$	-55 to +150	°C

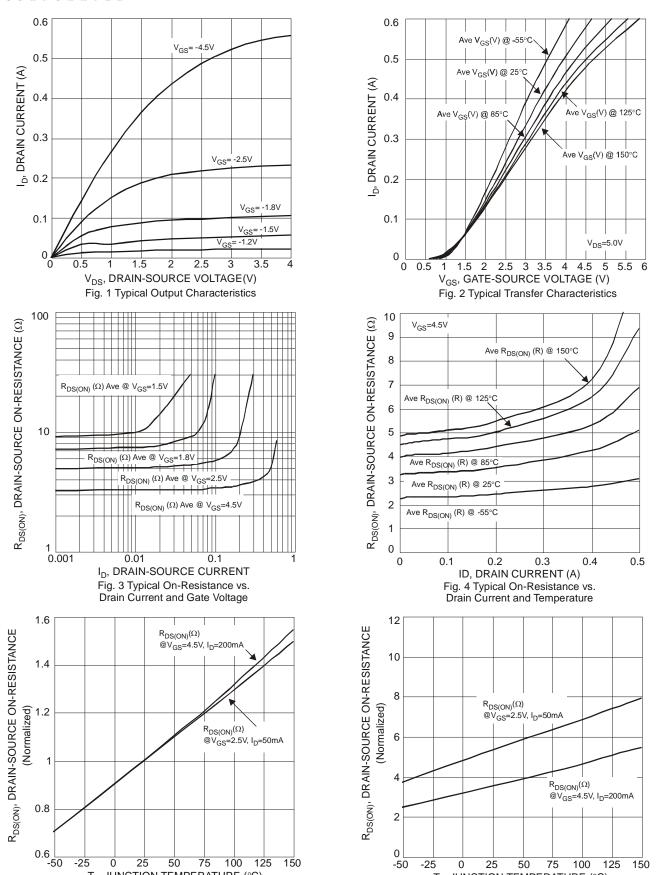
### Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 6)	OFF CHARACTERISTICS (Note 6)						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-20	_		V	$V_{GS} = 0V, I_{D} = -250\mu A$	
Zero Gate Voltage Drain Current	leas	_	_	-100	nA	$V_{DS} = -16V, V_{GS} = 0V$	
Zero Gate Voltage Brain Gurrent	I <sub>DSS</sub>	_	_	-50	nA	$V_{DS} = -5.0V, V_{GS} = 0V$	
				±100	nA	$V_{GS} = \pm 5.0V, V_{DS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±1	μΑ	$V_{GS} = \pm 8.0 V, V_{DS} = 0 V$	
				±10	μΑ	$V_{GS} = \pm 10.0 V, V_{DS} = 0 V$	
ON CHARACTERISTICS (Note 6)							
Gate Threshold Voltage @TJ:	= +25°C V <sub>GS(th)</sub>	-0.5	_	-1.0	V	$V_{DS} = V_{GS}$ , $I_D = -250\mu A$	
Gate Threshold Voltage (Note 7) @TJ	= 0°C	-0.55	_	-1.05			
@T <sub>J</sub>	$= +85^{\circ}C$ $V_{GS(th)}$	-0.40	_	-0.90	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
@T <sub>J</sub> =	+100°C	-0.35	_	-0.85			
		_	_	5		$V_{GS} = -4.5V, I_D = -100mA$	
		_	_	7	Ω	$V_{GS} = -2.5V, I_D = -50mA$	
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	_	_	10		$V_{GS} = -1.8V, I_D = -20mA$	
		_	_	15		$V_{GS} = -1.5V, I_D = -10mA$	
		_	20	_		$V_{GS} = -1.2V, I_D = -1mA$	
Forward Transfer Admittance	Y <sub>fs</sub>	_	200	_	mS	$V_{DS} = -10V, I_{D} = -200mA$	
Diode Forward Voltage (Note 5)	V <sub>SD</sub>	-0.5	_	-1.2	V	$V_{GS} = 0V, I_{S} = -115mA$	
DYNAMIC CHARACTERISTICS (Note 7)							
Input Capacitance	C <sub>iss</sub>	_	13.72	175	pF	15)/ )/ 0)/	
Output Capacitance	C <sub>oss</sub>		4.01	30	pF	$V_{DS} = -15V, V_{GS} = 0V$ f = 1.0MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>	_	2.34	20	pF	1 = 1.0WH12	
SWITCHING CHARACTERISTICS (Note 7)							
Turn-On Delay Time	t <sub>d(on)</sub>	_	7.7				
Rise Time	tr	_	19.3		nS	$V_{GS} = -4.5V, V_{DD} = -15V$ $I_{D} = -180\text{mA}, R_{G} = 2.0\Omega$	
Turn-Off Delay Time	t <sub>d(off)</sub>	_	25.9		113		
Fall Time	t <sub>f</sub>	_	31.5	_			

Notes:

- 5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
- Short duration pulse test used to minimize self-heating effect.
  Guaranteed by design. Not subject to production testing.





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T<sub>J</sub>, JUNCTION TEMPERATURE (°C)

Fig. 5 On-Resisitance Variation with Temperature

75

100

-25

-50

75

50

T<sub>J</sub>, JUNCTION TEMPERATURE (°C)

Fig. 6 On-Resisitance vs.Temperature

25

100



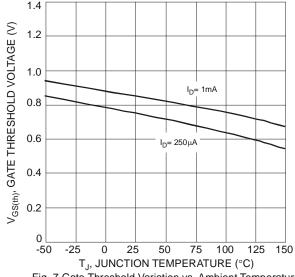
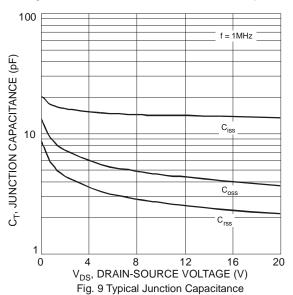
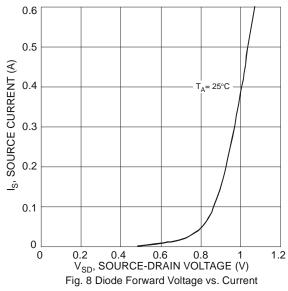


Fig. 7 Gate Threshold Variation vs. Ambient Temperature





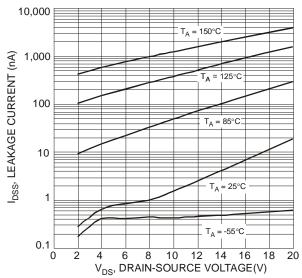


Fig. 10 Typical Drain-Source Leakage Current vs. Voltage

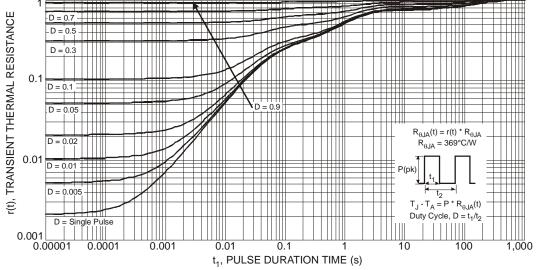


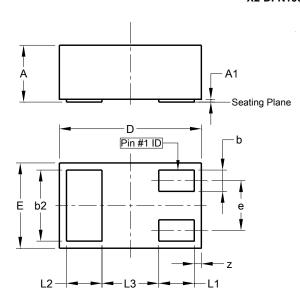
Fig. 11 Transient Thermal Response



# **Package Outline Dimensions**

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

#### X2-DFN1006-3

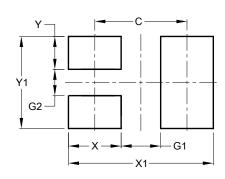


X2-DFN1006-3				
Dim	Min	Max	Тур	
Α		0.40	_	
A1	0.00	0.05	0.03	
b	0.10	0.20	0.15	
b2	0.45	0.55	0.50	
D	0.95	1.05	1.00	
Е	0.55	0.65	0.60	
е	-	-	0.35	
L1	0.20	0.30	0.25	
L2	0.20	0.30	0.25	
L3	•	-	0.40	
z	0.02	0.08	0.05	
All Dimensions in mm				

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.

#### X2-DFN1006-3



Dimensions	Value (in mm)
С	0.70
G1	0.30
G2	0.20
Х	0.40
X1	1.10
Y	0.25
V1	0.70



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